L Number	Hits	Search Text	DB	Time stamp
1	77641	356/\$.ccls.	USPAT;	2004/03/30
			US-PGPUB;	08:14
			EPO; JPO;	
			DERWENT; IBM TDB	
2	0	356/\$.ccls. and dielectric adj3 viod	USPAT;	2004/03/30
			US-PGPUB;	08:14
			EPO; JPO;	
			DERWENT; IBM TDB	
3	1	356/\$.ccls. and dielectric adj3 void	USPAT;	2004/03/30
		•	US-PGPUB;	08:14
			EPO; JPO;	
			DERWENT; IBM TDB	
4	16	356/\$.ccls. and layer adj3 void	USPAT;	2004/03/30
		1	US-PGPUB;	07:59
			EPO; JPO;	
			DERWENT; IBM TDB	
5	4759	356/237.1-237.5.ccls.	USPAT;	2004/03/30
1	.,,,,		US-PGPUB;	07:59
			EPO; JPO;	
			DERWENT;	
6	1	 356/237.1-237.5.ccls. and layer adj3 void	IBM_TDB USPAT;	2004/03/30
[]		330,237.1 237.3.0013. and layer adj3 void	US-PGPUB;	08:00
			EPO; JPO;	
[DERWENT;	
7	153	356/237.1-237.5.ccls. and void	IBM_TDB USPAT;	2004/03/30
'	153	356/25/.1-25/.5.001s. and Void	US-PGPUB;	08:15
			EPO; JPO;	
			DERWENT;	,
8	7.	(356/237.1-237.5.ccls. and void) and	IBM_TDB USPAT;	2004/03/30
6	/ 6	(356/237.1-237.3.0015. and void) and layer	US-PGPUB;	08:15
			EPO; JPO;	
			DERWENT;	
9	24	((356/237.1-237.5.cclsand_void)_ and	IBM_TDB USPAT; -	-2004/-03/-30
13		layer) and dielectric	US-PGPUB;	08:16
			EPO; JPO;	
			DERWENT;	
10	104682	250/\$.ccls.	IBM_TDB USPAT;	2004/03/30
10	103002	200,4.0013.	US-PGPUB;	08:14
			EPO; JPO;	
			DERWENT;	
11	0	250/\$.ccls. and dielectric adj3 viod	IBM_TDB USPAT;	2004/03/30
* *		200, 7. cold. and dielectric adjo viou	US-PGPUB;	08:14
			EPO; JPO;	
			DERWENT;	
12	6	250/\$.ccls. and dielectric adj3 void	IBM_TDB USPAT;	2004/03/30
**		200, 7. cold. and dielectic adjo void	US-PGPUB;	08:15
			EPO; JPO;	
			DERWENT;	
13	1520	250/\$.ccls. and void	IBM_TDB USPAT;	2004/03/30
13	1320	2007 7. CC13. and VOIG	US-PGPUB;	08:15
			EPO; JPO;	
1			DERWENT;	
14	863	(250/\$.ccls. and void) and layer	IBM_TDB USPAT;	2004/03/30
1 3	""	1200/9.0010. and vota/ and tayer	US-PGPUB;	08:15
			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	

15	250	((250/\$.ccls. and void) and layer) and	USPAT;	2004/03/30
		dielectric	US-PGPUB;	08:16
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	745674	processor	USPAT;	2004/03/30
1 **	, 150, 1	Processor	US-PGPUB;	08:16
			EPO; JPO;	00.10
			DERWENT;	
_			IBM_TDB	, ,
17	58		USPAT;	2004/03/30
		dielectric) and processor	US-PGPUB;	08:17
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
18	221	(((250/\$.ccls. and void) and layer) and	USPAT;	2004/03/30
"		dielectric) and (wafer or substrate)	US-PGPUB;	08:17
		diciccitie , and (water or substitute)	EPO; JPO;	00.17
			DERWENT;	
			IBM_TDB	
19	52		USPAT;	2004/03/30
		dielectric) and (wafer or substrate))	US-PGPUB;	08:17
		and processor	EPO; JPO;	
		-	DERWENT;	
i			IBM TDB	ļ l
l _	2	("6134002").PN.	USPAT;	2004/03/24
	"	1 , 223,000 / , 2	US-PGPUB;	14:20
			EPO; JPO;	13.20
	ļ			
			DERWENT;	
			IBM_TDB	1
-	77564	356/\$.CCLS.	USPAT;	2004/03/24
			US-PGPUB;	15:48
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	935	((356/\$).CCLS.) and ((wafer or substrate)	USPAT;	2004/03/24
		adj3 (tilt or angle))	US-PGPUB;	15:48
		days (circ or angre))	EPO; JPO;	10.30
			DERWENT;	
	_	(#655,6000#) 777	IBM_TDB	2004/02/24
_	2	("6556290").PN.	USPAT;	2004/03/24
			US-PGPUB;	14:35
	<u></u>		EPO; JPO;	
[DERWENT;	
			IBM_TDB	
-	0	(356/\$.ccls. and dielectric adj3 void)	USPAT;	2004/03/24
		and ((beam adj2 splitter) or	US-PGPUB;	15:06
		(beamsplitter))	EPO; JPO;	
		\	DERWENT;	
			IBM TDB	
l _	0	/356/6 cale and lawar addaid/ and	USPAT;	2004/03/24
-	1	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		1 1
		reflected	US-PGPUB;	14:46
			EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	
-	0	(356/\$.ccls. and dielectric adj3 viod)	USPAT;	2004/03/24
		and ((wafer or substrate) adj3 (tilt))	US-PGPUB;	15:06
		', ', ', ', ', ', ', ', ', ', ', ', ',	EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	0	(356/237.1-237.5.ccls. and layer adj3	USPAT;	2004/03/24
i ⁻				15:21
		void) and ((beam adj2 splitter) or	US-PGPUB;	13:41
		(beamsplitter))	EPO; JPO;	
			DERWENT;	
Ì			IBM_TDB	, , ,
-	0	(356/\$.ccls. and dielectric adj3 void)	USPAT;	2004/03/24
		and 356/138-155.ccls.	US-PGPUB;	15:22
1			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
ı	1	I		